

Amendments to the Abstract:

Please replace the paragraph beginning at page 6, line 2, with the following rewritten paragraph:

- An integrated circuit package ~~having central leads~~ comprises a substrate
5 has ~~having~~ an upper surface, a lower surface, and a long slot penetrating from the
upper surface to the lower surface. The lower surface is ~~forming~~ formed with a
wiring regions arranged at ~~the two sides~~ one side of the long slot, and the wiring
regions ~~are~~ is forming formed with a plurality of ~~connected~~ connection points. A
glue layer is coated on the upper surface of the substrate and is arranged at the
10 periphery of the long slot. The integrated circuit has a first surface ~~forming~~
formed with a plurality of bonding pads and, ~~which~~ is adhered to the glue layer.
The wires, each of which is arranged within the long slot of the substrate, ~~and is~~
electrically connected the bonding pads of the integrated circuit to the ~~connected~~
connection points of the substrate, ~~;~~ ~~and~~ The first compound layer is filled within
15 the long slot of the substrate ~~for protecting to protect~~ the ~~each~~ wires. --